

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

QFN 4mm X 4mm Exp. Pad

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TOTAL MASS (g) : 0.037197

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|--------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001662 | 1000000 | 44680.6328125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.012129 | 975000 | 326071.84375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000299 | 24000 | 8038.21240234 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 107.534614563 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000009 | 700 | 241.952896118 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.012441 | 1000000 | 334459.53125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000580 | 1000000 | 15601.3125 | | |
| | | External Plating Total: | | | | 0.000580 | 1000000 | 15601.3125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000278 | 1000000 | 7473.65527344 | | |
| Internal Plating Total: | | | | 0.000278 | 1000000 | 7473.65527344 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000800 | 750000 | 21506.921875 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000267 | 250000 | 7177.93554688 | | |
| Die Attach Total: | | | | 0.001067 | 1000000 | 28684.8574219 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002739 | 130000 | 73634.328125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.018120 | 860000 | 487131.8125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000211 | 10000 | 5672.45117188 | | |
| | | Encapsulation Total: | | | | 0.021070 | 1000000 | 566438.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000099 | 1000000 | 2661.48144531 | | |
| | | | | | TOTAL MASS (g) : | 0.037197 | | |